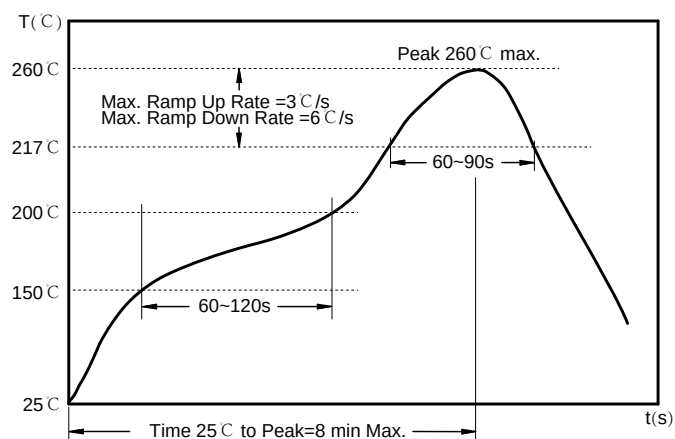


Soldering Reflow:



Preheat condition: 150 ~200 °C / 60~120 sec.

Allowed time above 217 °C: 60~90 sec.

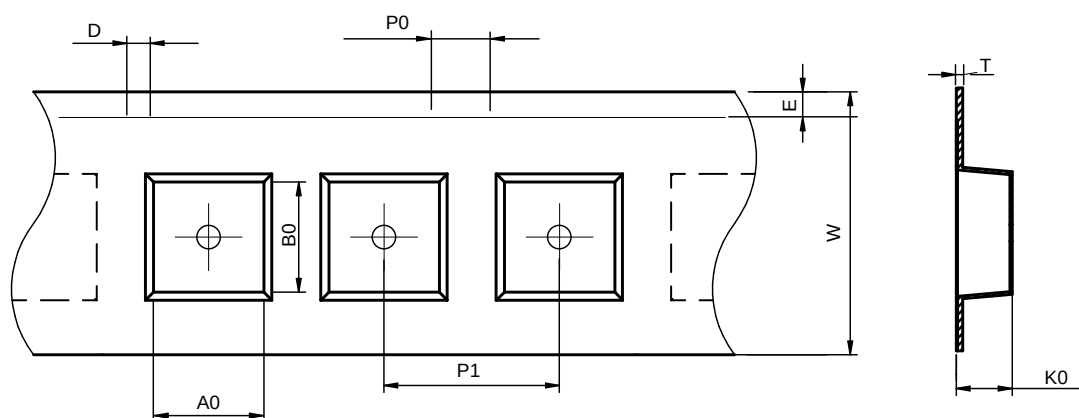
Max temperature: 260 °C.

Max time at max temperature: 10 sec.

Allowed Reflow time: 2x max.

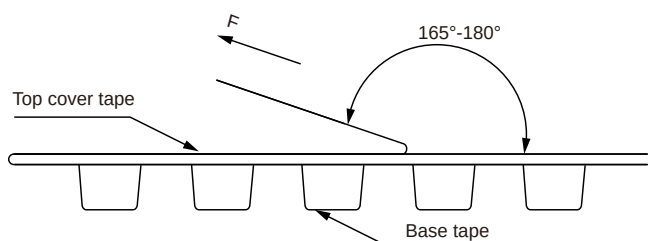
Packaging Information:

Tape Dimension:



Series	A0 (mm)	B0 (mm)	D (mm)	P0 (mm)	P1 (mm)	W (mm)	K0 (mm)	E (mm)	T (mm)
MDTE6030	7.0 ± 0.1	6.8 ± 0.1	1.5 ± 0.1	4.0 ± 0.1	12.0 ± 0.1	16.0 ± 0.3	3.3 ± 0.1	1.75 ± 0.1	0.35 ± 0.05

Peel force of top cover tape:

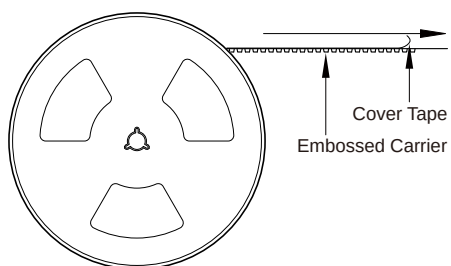


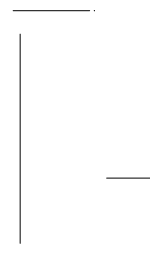
The peel force of top cover tape shall be between 0.1 to 1.3 N

Product Marking:

Marking	Printing Inductance)
---------	----------------------

Reel Dimension: [mm]





Packaging Quantity: